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In re Patent Application of:

Applicant: Hewlett-Packard Company

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Applicants' Reference No: 10004808-1

Title: Process for High-Dielectric Constant Metal-Insulator Metal Capacitor in VLSI Multi-Level Metallization Systems

BOX NON FEE AMENDMENTS

Commissioner for Patents
Washington, D.C. 20231

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Letter in Response to Notice of Restriction

GROUP 3600

In response to the Notice of Restriction, Applicant elects Group I claims and hereby cancels the non-elected claims.

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Respectfully submitted,

Hewlett-Packard Company

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I hereby certify that this correspondence is being deposited on the date indicated below with the United States Postal Service as First Class Mail.


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